

notches on the corresponding edges of said receptacle and such removable information processing units.

5. The combination according to claim 4 wherein said inlaid information processing unit comprises an inlaid microprocessor, and the removable information processing units comprise integrated circuit microprocessor systems embedded in nonconductive material with exposed terminals thereon for making electrical contact with said network bus conductor.

6. The combination according to claim 5 wherein said card body comprises a laminate of at least two layers, a first layer thereof having said network bus conductor thereon and the second layer thereof having said inlaid information processing unit therein and having said receptacle in the form of a hole therethrough, said second layer being bonded to said first layer to align the hole therethrough over said network bus conductor on said second layer to expose said network bus conductor in the hole through said second layer.

7. The combination according to claim 6 wherein said network bus conductor includes a plurality of bus conductors extending in parallel with one another and in parallel with the first surface of said card body.

8. The combination according to claim 7 wherein said retaining means comprises a conductive plate movably attached to the first surface of said card body for movement in a plane parallel to such first surface between a first position overlying said open receptacle to a second position exposing said receptacle.

9. The combination according to claim 8 further including a plurality of open receptacles, each extending from the first surface of said card body to a depth to expose said network bus conductor therein in each of said receptacles.

10. The combination according to claim 7 wherein said retaining means is made of electrically conductive material.

11. The combination according to claim 1 wherein said retaining means comprises a conductive plate movably attached to the first surface of said card body for movement in a plane parallel to such first surface between a first position overlying said open receptacle to a second position exposing said receptacle.

12. The combination according to claim 1 wherein said retaining means is made of electrically conductive material.

13. The combination according to claim 1 wherein said card body comprises a laminate of at least two layers, a first layer thereof having said network bus

conductor thereon and the second layer thereof having said inlaid information processing unit therein and having said receptacle in the form of a hole therethrough, said second layer being bonded to said first layer to align the hole therethrough over said network bus conductor on said second layer to expose said network bus conductor in the hole through said second layer.

14. The combination according to claim 1 wherein said network bus conductor includes a plurality of bus conductors extending in parallel with one another and in parallel with the first surface of said card body.

15. An IC card including in combination:

a card body of a predetermined thickness having a first surface and having a network bus conductor therein at a distance from said first surface which is less than said predetermined thickness;

an inlaid information processing unit in said card body having external signal connection terminals on an exposed face thereof at said first surface of said card body and electrically interconnected with said network bus conductor;

a plurality of open receptacles extending from the first surface of said card body to a depth to expose said network bus conductor in each of said receptacles for electrical contact with conductive terminals of different removable information processing units configured to fit into each of said receptacles.

16. The combination according to claim 15 further including means associated with each of said receptacles for ensuring a pre-determined orientation of removable information processing units placed into each said receptacle.

17. The combination according to claim 16 wherein said orienting means comprises mating projections and notches on the corresponding edges of each of said receptacles and such removable information processing units.

18. The combination according to claim 15 wherein said inlaid information processing unit comprises an inlaid microprocessor, and the removable information processing units comprise integrated circuit microprocessor systems embedded in nonconductive material with exposed terminals thereon for making electrical contact with said network bus conductor.

19. The combination according to claim 1 wherein said inlaid information processing unit includes a signal processing integrated circuit.

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